

## Product/Process Change Notice - PCN 12\_0130 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

**PCN Title:** ADP1877 - Bond Wire Change

Publication Date: 07-Jun-2012

Effectivity Date: 05-Sep-2012 (the earliest date that a customer could expect to receive changed material)

nitial Release	
Description Of Change	
Change from Gold Bond Wire to Copper Bond Wire.	
Reason For Change	
Aligns with ADI strategic initiative to utilize copper wire bond in select applications.	
mpact of the change (positive or negative) on fit, form, function & reliability	
Product Identification (this section will describe how to identify the changed material)	
The material will be identified by the transition date recorded by the date code. Only the bonding diagram will change.	

## **Supporting Documents**

Attachment 1: Type: Qualification Report Summary

Attached rel report can be provided to the customer.

ADI\_PCN\_12\_0130\_Rev\_-\_ADP1877\_PCN\_12\_0130\_SCM.doc

	For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative						
Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan: Rest of Asia:	PCN_Japan@analog.com PCN_ROA@analog.com		

## Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (1)

ADP1877 / ADP1877ACPZ-R7			
1			4

Appendix B - Revision History					
Rev	Publish Date	Effectivity Date	Rev Description		
Rev	07-Jun-2012	05-Sep-2012	Initial Release		

Analog Devices, Inc.

Docld:1989 Parent Docld:None Layout Rev.7